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Attorney Docket No. <u>450100-04316</u>

Applicant(s)	:	Eriko MATSUI et al.
For	:	METAL COMPLEX OF HETEROCYCLIC AROMATIC COMPOUND
Corresponding Int'l Appln.	:	PCT/JP02/13228
International Filing Date	:	December 18, 2002

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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1. Names of Conveying Parties : Eriko MATSUI, Yuriko KAINO, Toshiyuki KUNIKIYO, Tatsushiro HIRATA, Yoshifumi MORI

2. Names and addresses of receiving parties :
Sony Corporation
7-35, Kitashinagawa 6-chome,
Tokyo 141-0001, Japan

3. Nature of Conveyance : Assignment.
Execution Dates : July 2, July 2, July 3, July 4 and July 5, 2003

4. ☐ Application No.:
☒ This document is being filed together with a new application, the execution date of the application is: July 2, July 2, July 3, July 4 and July 5, 2003

5. Name and address of party to whom the recorded assignment and any correspondence concerning the document should be mailed:

William S. Frommer
Registration No. 25,506
FROMMER LAWRENCE & HAUG LLP
745 Fifth Avenue
New York, New York 10151.

6. Total number of applications and patents involved: 1.
7. Total Fee (37 CFR 3.41): $40.00.
☒ Fee enclosed.
8. ☐ Charge Fee Deposit Account No. 50-0320 (Attach duplicate copy of this page if paying by deposit account).
☒ If any additional fee is required, authorization is hereby given to charge Deposit Account No. 50-0320.
9. Statement and Signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William S. Frommer, Esq.	William Frommer	August 25, 2003
Name of Person Signing	Signature	Date

00143003

S02P1588US00
CMS Docket Number: 450100-04316

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
METAL COMPLEX OF HETEROCYCLIC AROMATIC COMPOUND

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: PCT/JP02/13228, Filing Date: DECEMBER 18, 2002

This assignment executed on the dates indicated below.

ERIKO MATSUI
Name of first or sole inventor | Execution date of U.S. Patent Application
KANAGAWA, JAPAN
Residence of first or sole inventor
Eriko Matsui | July 2, 2003
Signature of first or sole inventor | Date of this assignment

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Signature of second inventor | Date of this assignment

TOSHIYUKI KUNIKIYO
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Residence of third inventor
Toshiyuki Kunikiyo | July 3, 2003
Signature of third inventor | Date of this assignment

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Residence of fourth inventor	
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Signature of fourth inventor	Date of this assignment
YOSHIFUMI MORI	
Name of fifth inventor	Execution date of U.S. Patent Application
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Residence of fifth inventor	
Signature of fifth inventor	Date of this assignment
Name of sixth inventor	Execution date of U.S. Patent Application
Residence of sixth inventor	
Signature of sixth inventor	Date of this assignment
Name of seventh inventor	Execution date of U.S. Patent Application
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Signature of seventh inventor	Date of this assignment
Name of eighth inventor	Execution date of U.S. Patent Application
Residence of eighth inventor	
Signature of eighth inventor	Date of this assignment
Name of ninth inventor	Execution date of U.S. Patent Application
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TATSUSHIRO HIRATA

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Residence of fourth inventor

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YOSHIFUMI MORI

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CHIBA, JAPAN

Residence of fifth inventor

Yoshifumi Mori — July 5, 2003

Signature of fifth inventor — Date of this assignment

Name of sixth inventor — Execution date of U.S. Patent Application

Residence of sixth inventor

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Name of seventh inventor — Execution date of U.S. Patent Application

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Name of ninth inventor — Execution date of U.S. Patent Application

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